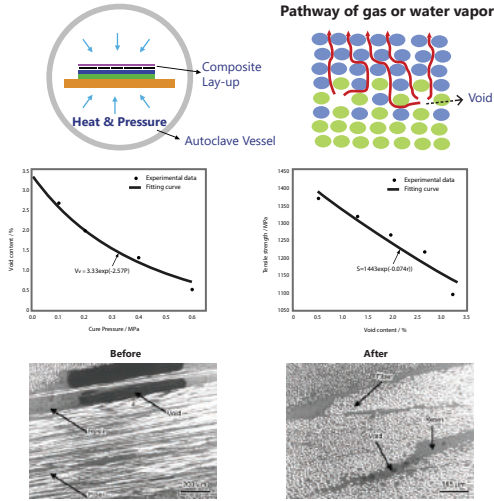


# HIGH PRESSURE OVEN

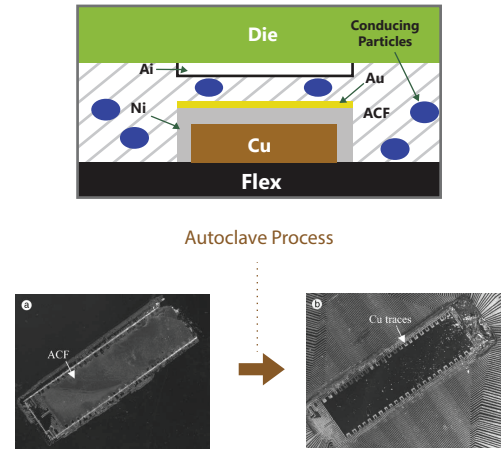
It has application of touch panel and film, semiconductor industry to remove voids.

## Removal of Void (Film, Carbon/Epoxy)



Ref. J. Mater. Sci. Technol., 27(1), (2011) 69-73

## Laminated Films (Anisotropic Conductive Film, Flip Chip)



Ref. Mater. Sci. Eng. B., 98, (2003) 255-264

temperature  
(200 °C)

경화공정 가능

Pressure  
[60 kg/cm<sup>2</sup>]

등방향 가압  
[접착강도 및 밀도증가]

